

CENG 4480 L09 Memory 2

Bei Yu

Reference:

- Chapter 11 Memories
- CMOS VLSI Design—A Circuits and Systems Perspective
- by H.E.Weste and D.M.Harris

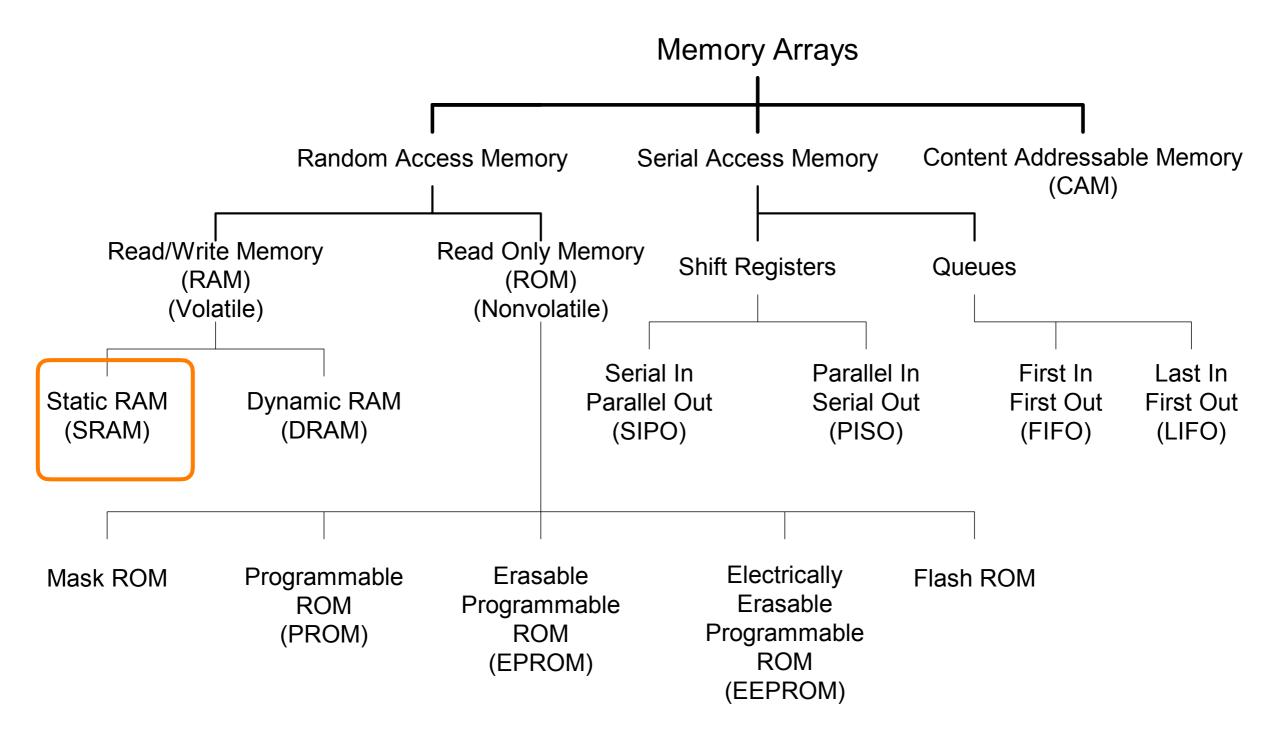
CENG4480 v.s. CENG3420

• CENG3420:

- architecture perspective
- memory coherent
- data address

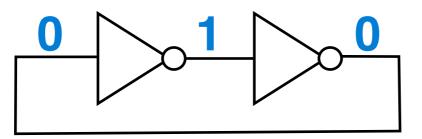
• CENG4480: more details on how data is stored

Memory Arrays

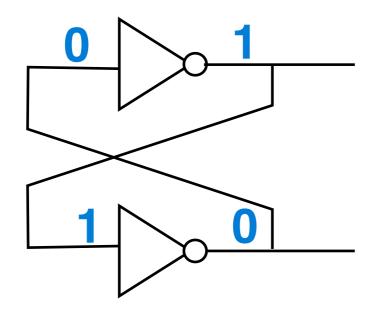


Storage based on Feedback

• What if we add feedback to a pair of inverters?



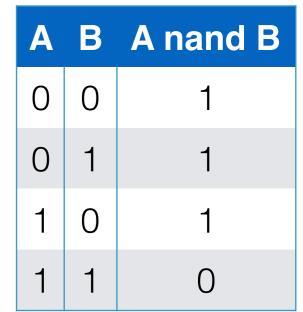
- Usually drawn as a ring of cross-coupled inverters
- Stable way to store one bit of information (w. power)

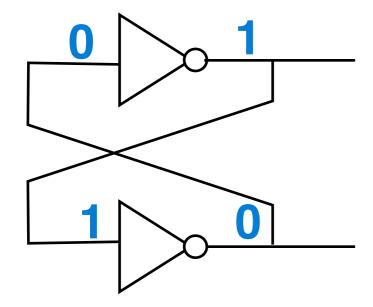


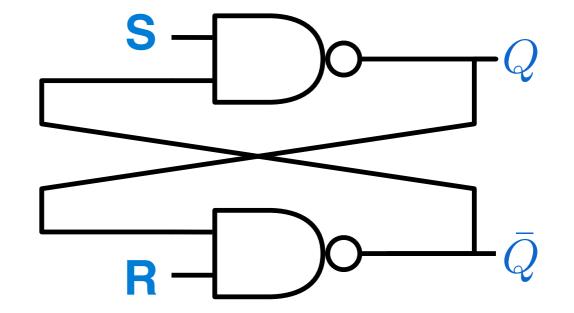


How to change the value stored?

- Replace inverter with NAND gate
- RS Latch

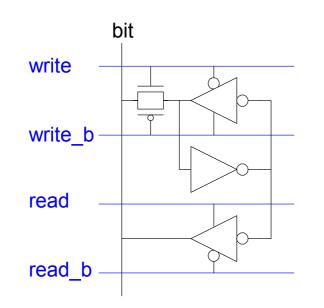


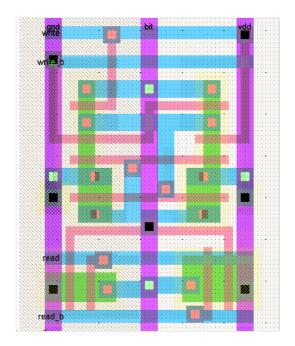




12T SRAM Cell

- Basic building block: SRAM Cell
 - Holds one bit of information, like a latch
 - Must be read and written
- 12-transistor (12T) SRAM cell
 - Use a simple latch connected to bitline
 - 46 x 75 λ unit cell





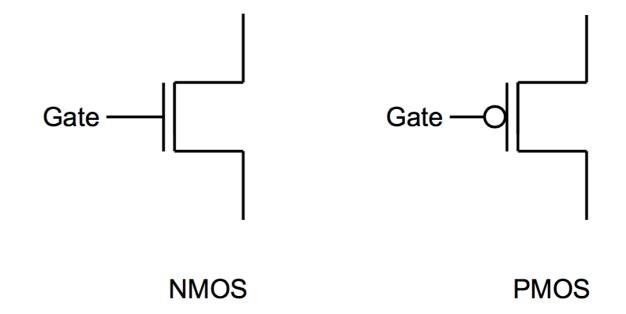
L09. Memory-2

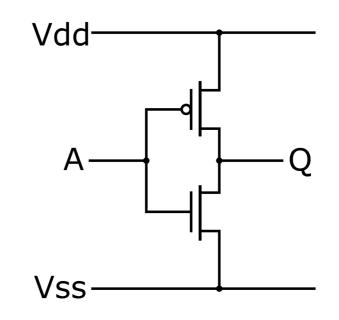
nMOS, pMOS, Inverter

• nMOS:

- Gate = 1, transistor is ON
- Then electric current path
- pMOS:
 - Gate = 0, transistor is ON
 - Then electric current path

- Inverter:
 - ◆ Q = NOT (A)





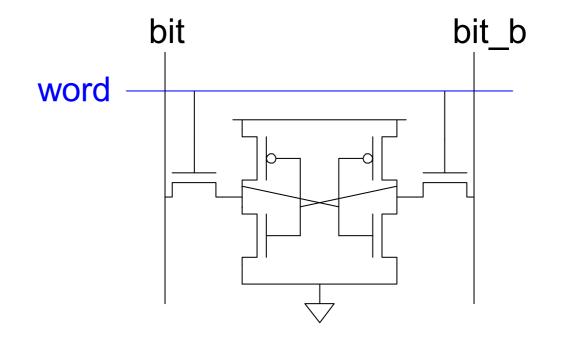
L09. Memory-2

6T SRAM Cell

- Used in most commercial chips
- A pair of weak cross-coupled inverters
- Data stored in cross-coupled inverters
- Compared with 12T SRAM, 6T SRAM:
 - (+) reduce area

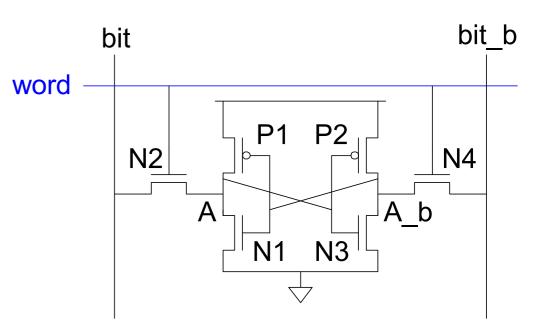
CENG4480

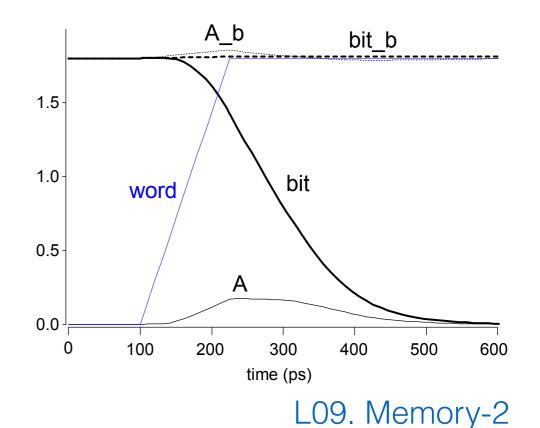
(-) much more complex control



6T SRAM Read

- Precharge both bitlines high
- Then turn on wordline
- One of the two bitlines will be pulled down by the cell
- Read stability
 - A must not flip
 - N1 >> N2

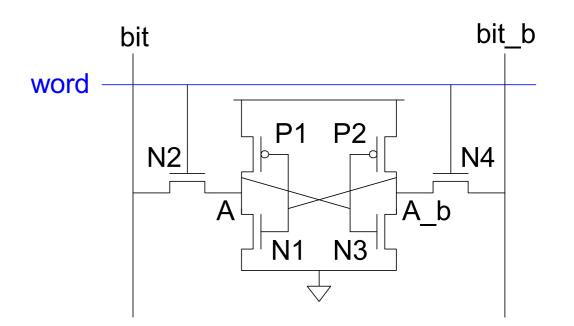




EX: 6T SRAM Read

• Question 1: A = 0, A_b = 1, discuss the behavior:

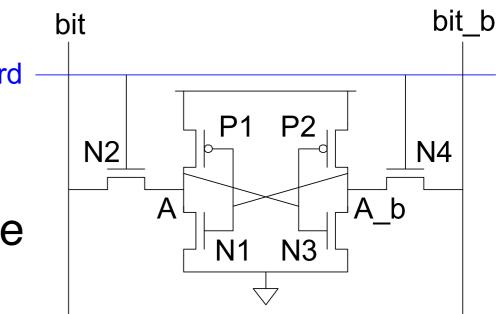
• Question 2: At least how many bit lines to finish read?

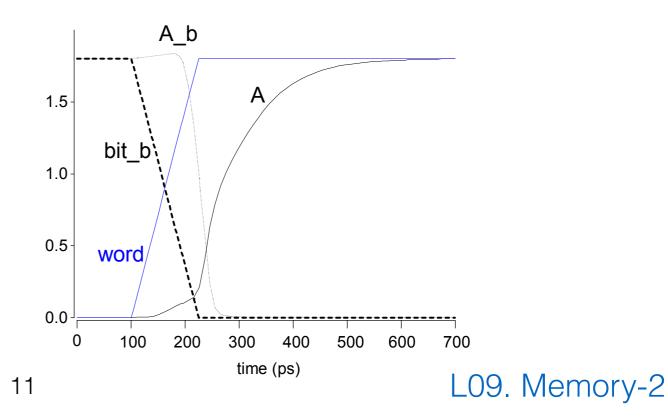


L09. Memory-2

6T SRAM Write

- Drive one bitline high, the other lowword
- Then turn on wordline
- Bitlines overpower cell with new value
- Writability
 - Must overpower
 - feedback inverter
 - N4 >> P2
 - N2 >> P1 (symmetry)

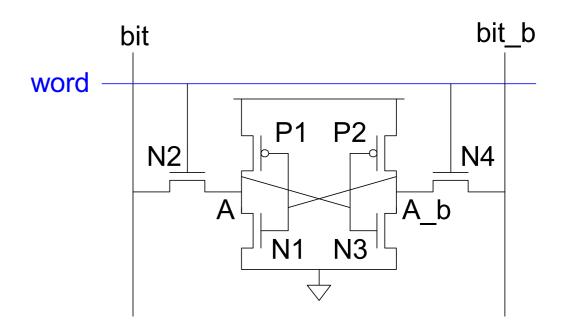




EX: 6T SRAM Write

• Question 1: A = 0, A_b = 1, discuss the behavior:

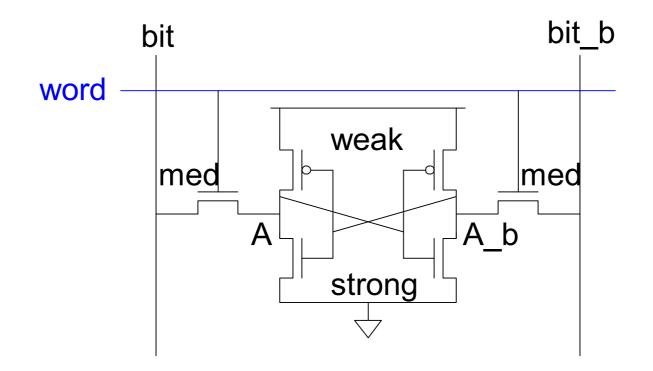
• Question 2: At least how many bit lines to finish write?



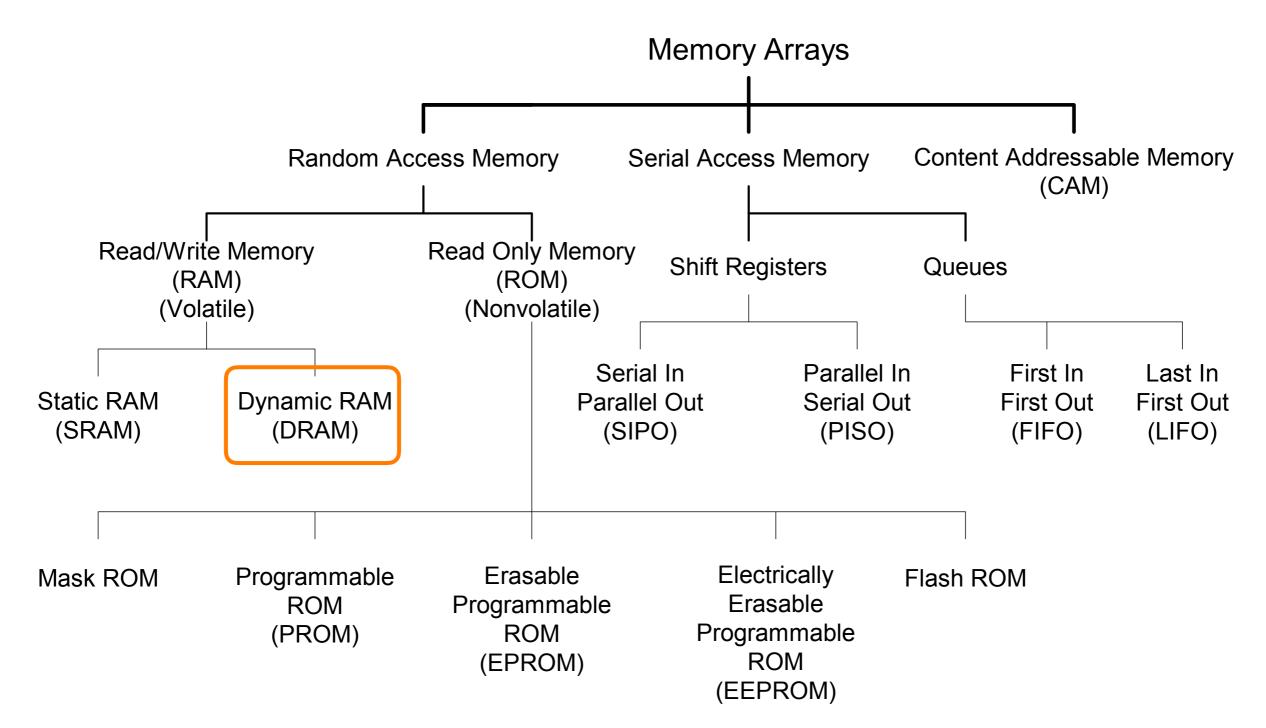
L09. Memory-2

6T SRAM Sizing

- High bitlines must not overpower inverters during reads
- But low bitlines must write new value into cell



Memory Arrays

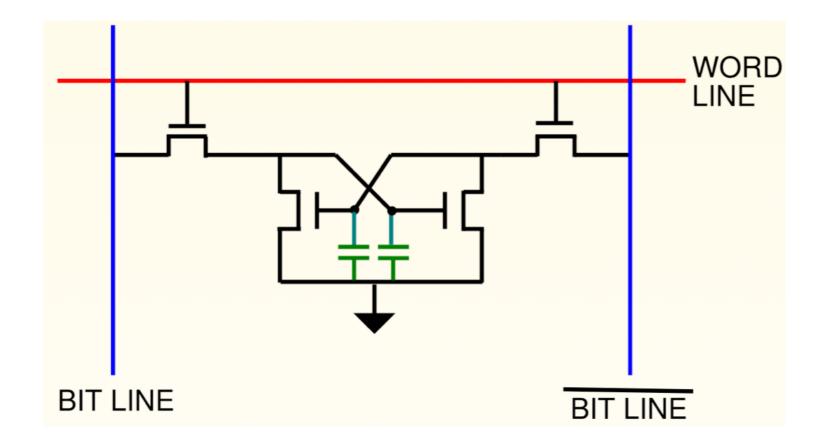


Dynamic RAM (DRAM)

- Basic Principle: Storage of information on capacitors
- Charge & discharge of capacitor to change stored value
- Use of transistor as "switch" to:
 - Store charge
 - Charge or discharge

4T DRAM Cell

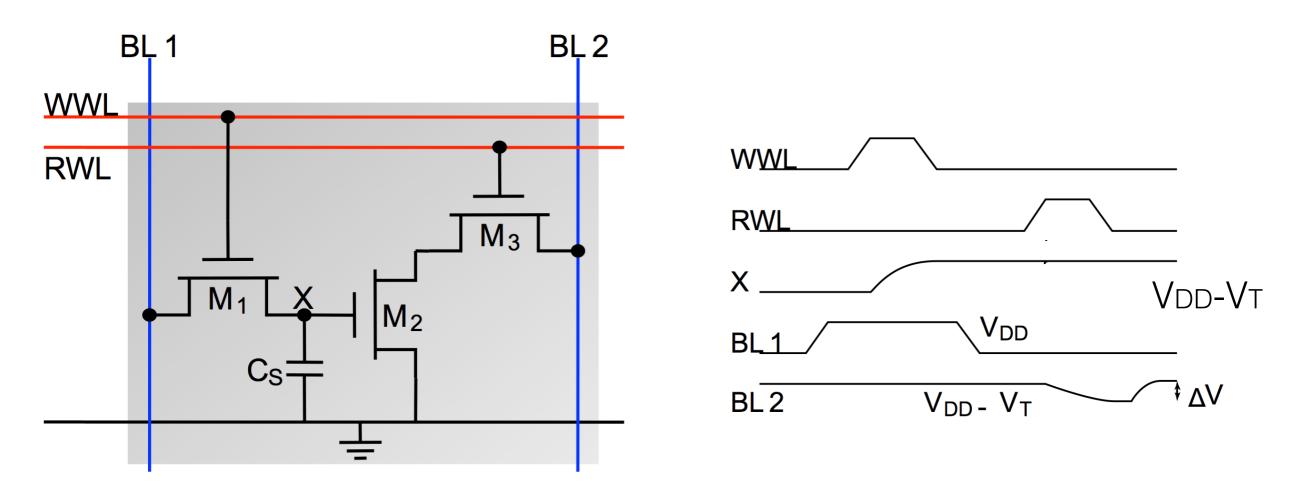
Remove the two p-MOS transistors from static RAM cell, to get a four-transistor dynamic RAM cell.



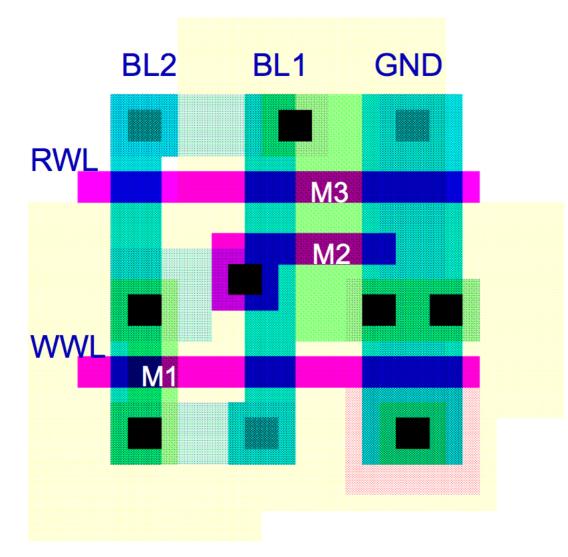
- Data must be refreshed regularly
- Dynamic cells must be designed very carefully
- Data stored as charge on gate capacitors (complementary nodes)

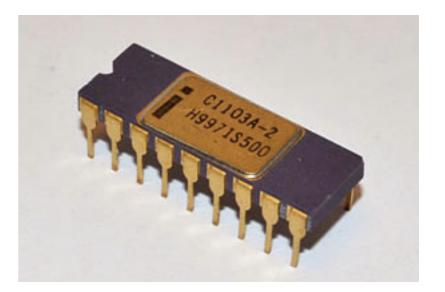
3T DRAM Cell

- No constraints on device ratios
- Reads are non-destructive
- Value stored at node X when writing a "1" = $V_{DD}-V_T$



3T DRAM Layout

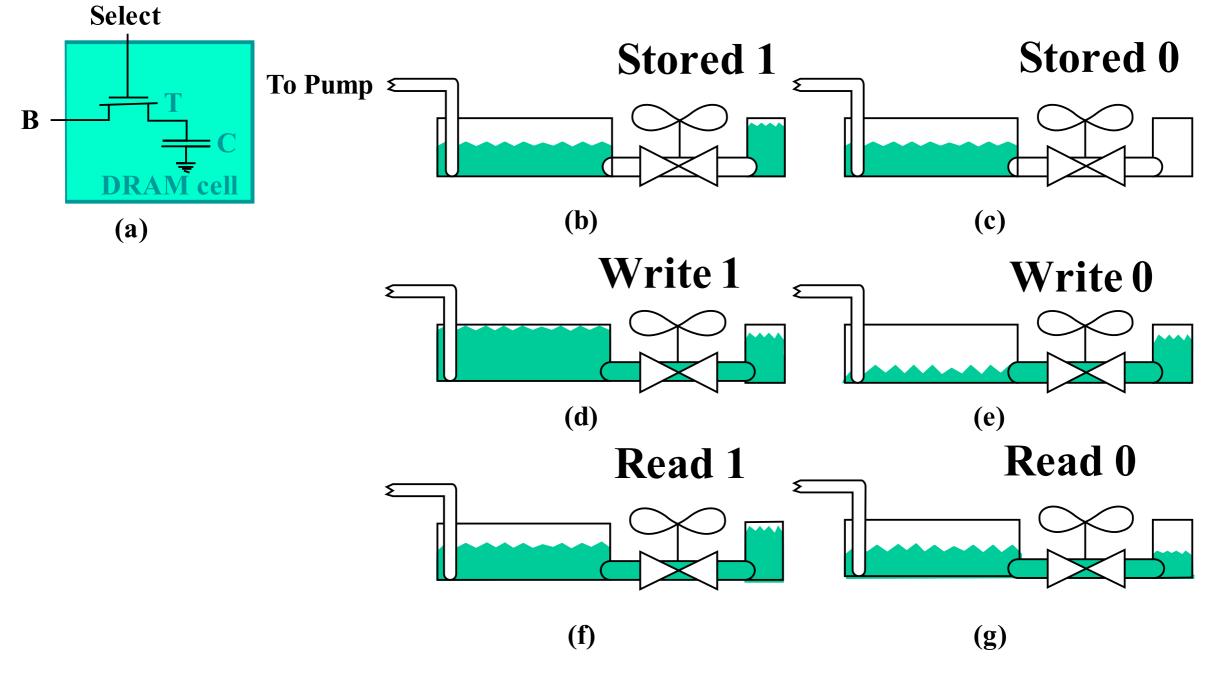




[1970: Intel 1003]

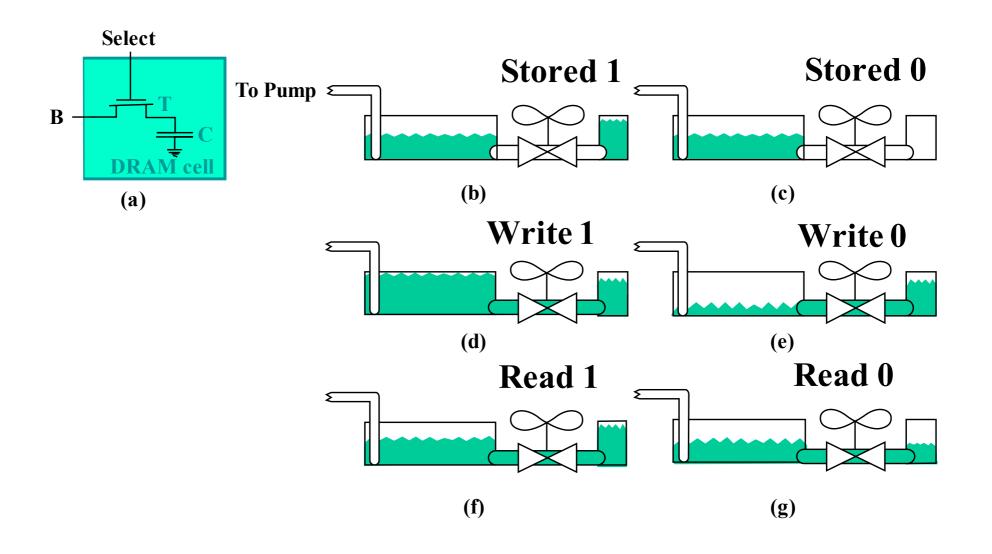
- 576 λ 3T DRAM v.s. 1092 λ 6T SRAM
- Further simplified

1T DRAM Cell



Need sense amp helping reading

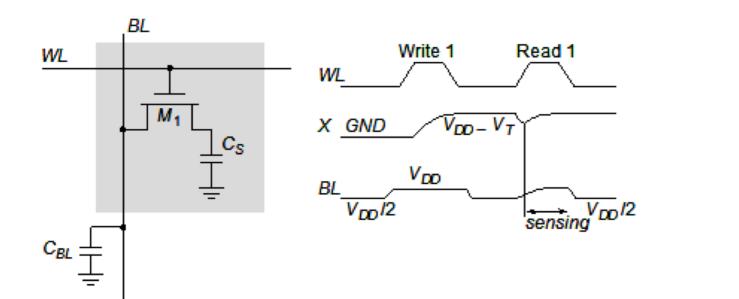
L09. Memory-2

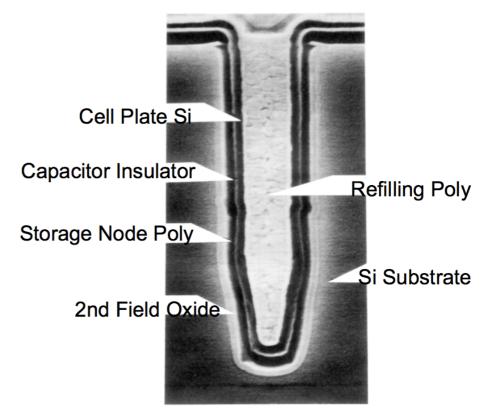


- Read:
 - Pre-charge large tank to VDD/2
 - If Ts = 0, for large tank : VDD/2 V1
 - If Ts = 1, for large tank: VDD/2 + V1
 - V1 is very insignificant
 - Need sense amp

1T DRAM Cell

- Write: Cs is charged or discharged by asserting WL and BL
- Read: Charge redistribution takes place between bit line and storage capacitance
- Voltage swing is small; typically around 250 mV





Trench-capacitor cell [Mano87]

L09. Memory-2

EX. 1T DRAM Cell

- Question: VDD=4V, CS=100pF, CBL=1000pF. What's the voltage swing value?
- Note: $\Delta V = \frac{V_{DD}}{2} \cdot \frac{C_S}{C_S + C_{BL}}$

SRAM v.s. DRAM

Static (SRAM)

- Data stored as long as supply is applied
- Large (6 transistors/cell)
- Fast
- Compatible with current CMOS manufacturing

Dynamic (DRAM)

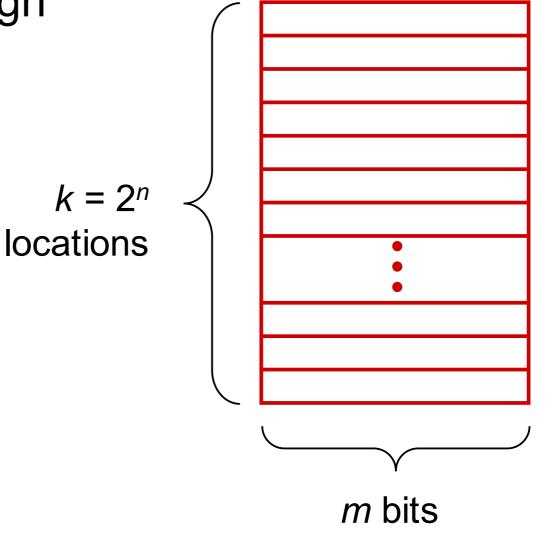
- Periodic refresh required
- Small (1-3 transistors/cell)
- Slower
- Require additional process for trench capacitance

Array Architecture

2ⁿ words of 2^m bits each

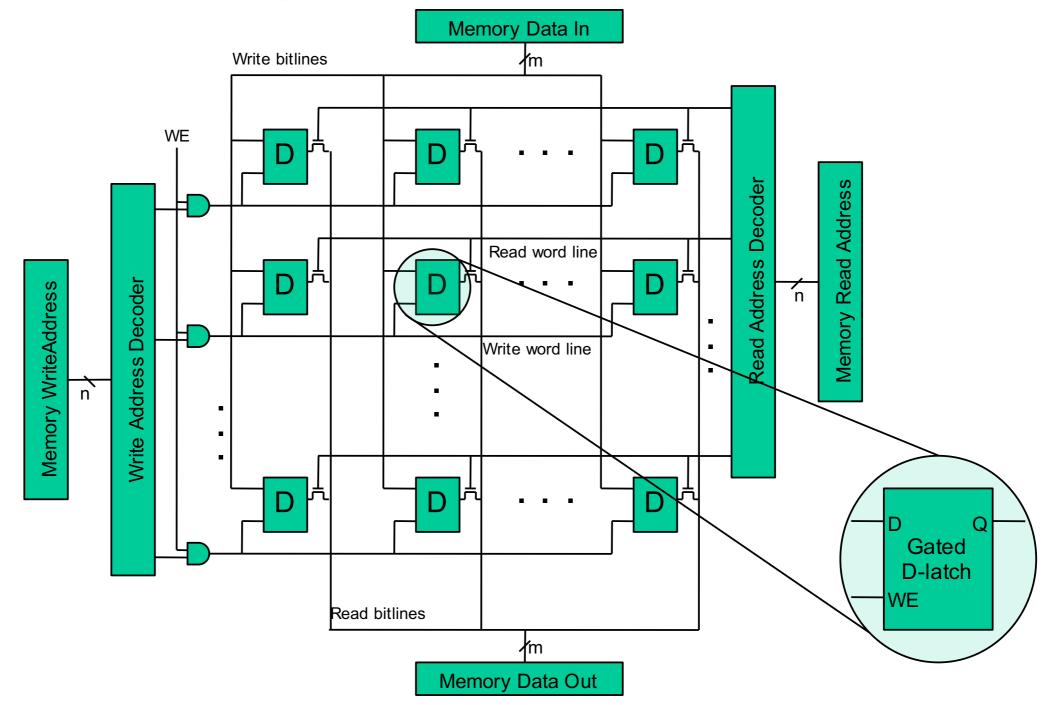
CENG4480

Good regularity – easy to design



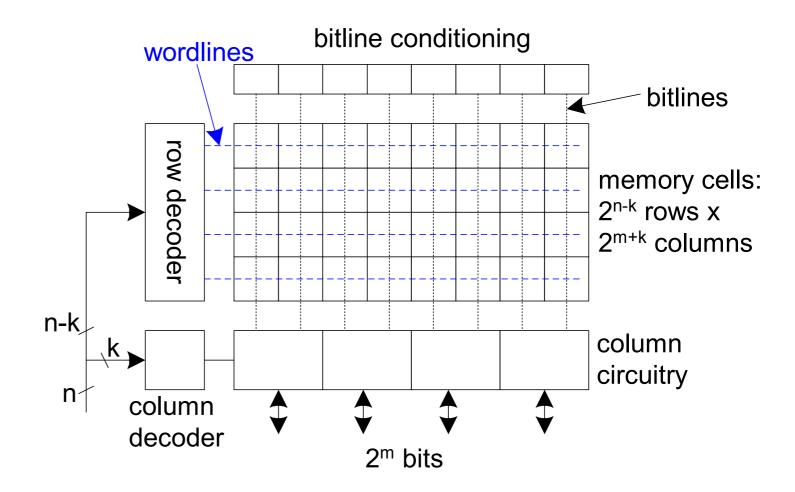
SRAM Memory Structure

Latch based memory



Array Architecture

- 2ⁿ words of 2^m bits each
- How to design if n >> m?
- Fold by 2k into fewer rows of more columns



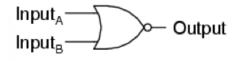
Decoders

- n:2ⁿ decoder consists of 2ⁿ n-input AND gates
 - One needed for each row of memory
 - Build AND with NAND or NOR gates

Static CMOS

CENG4480

Using NOR gates



Output

1

0

0

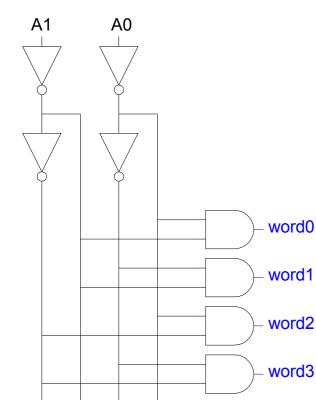
в

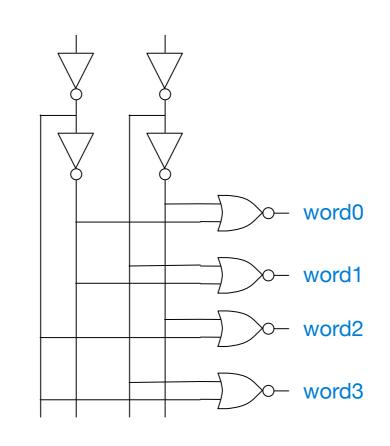
А

0 1

0 0

1 0

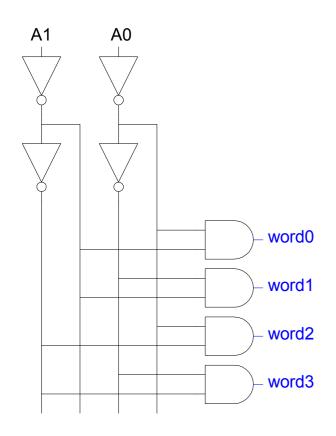






EX. Decoder

Question: AND gates => NAND gate structure

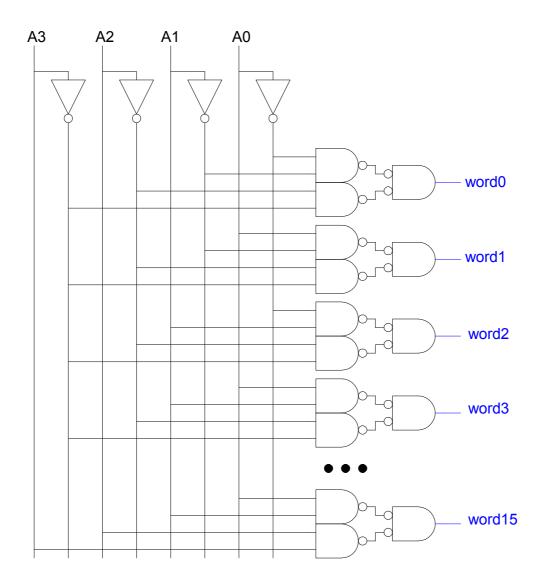


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Large Decoders

- For n > 4, NAND gates become slow
 - Break large gates into multiple smaller gates

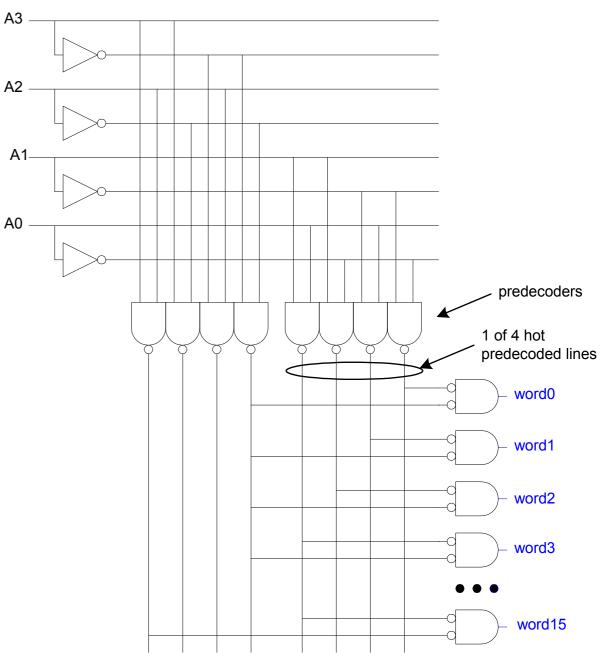


L09. Memory-2

Predecoding

Many of these gates are redundant _{A2}

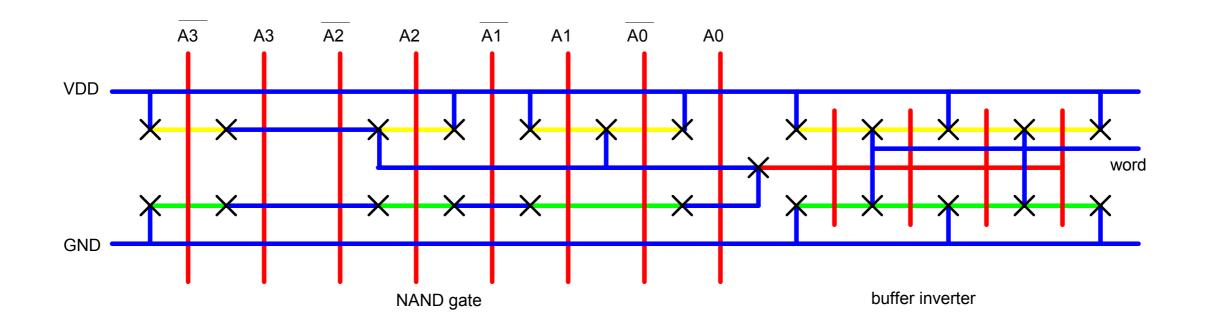
- Factor out common gates
- => Predecoder
- Saves area
- Same path effort



• Question: How many NANDs can be saved?

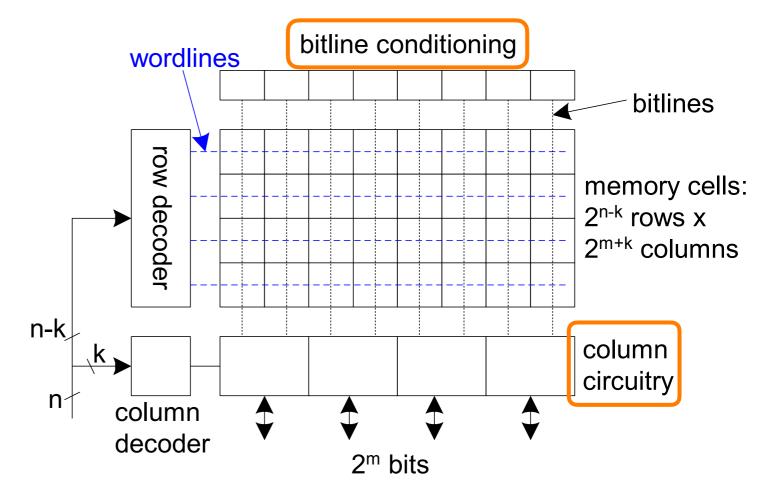
*Decoder Layout

- Decoders must be pitch-matched to SRAM cell
 - Requires very skinny gates



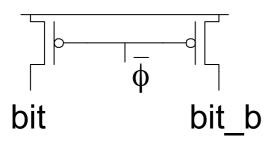
*Column Circuitry

- Some circuitry is required for each column
 - Bitline conditioning
 - Column multiplexing
 - *Sense amplifiers (DRAM)

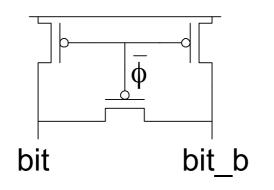


*Bitline Conditioning

• Precharge bitlines high before reads

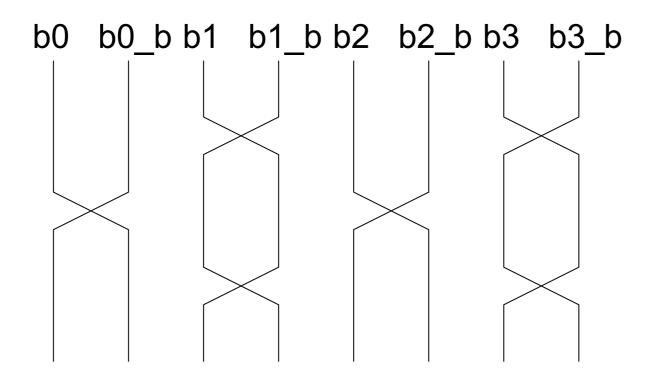


 Equalize bitlines to minimize voltage difference when using sense amplifiers

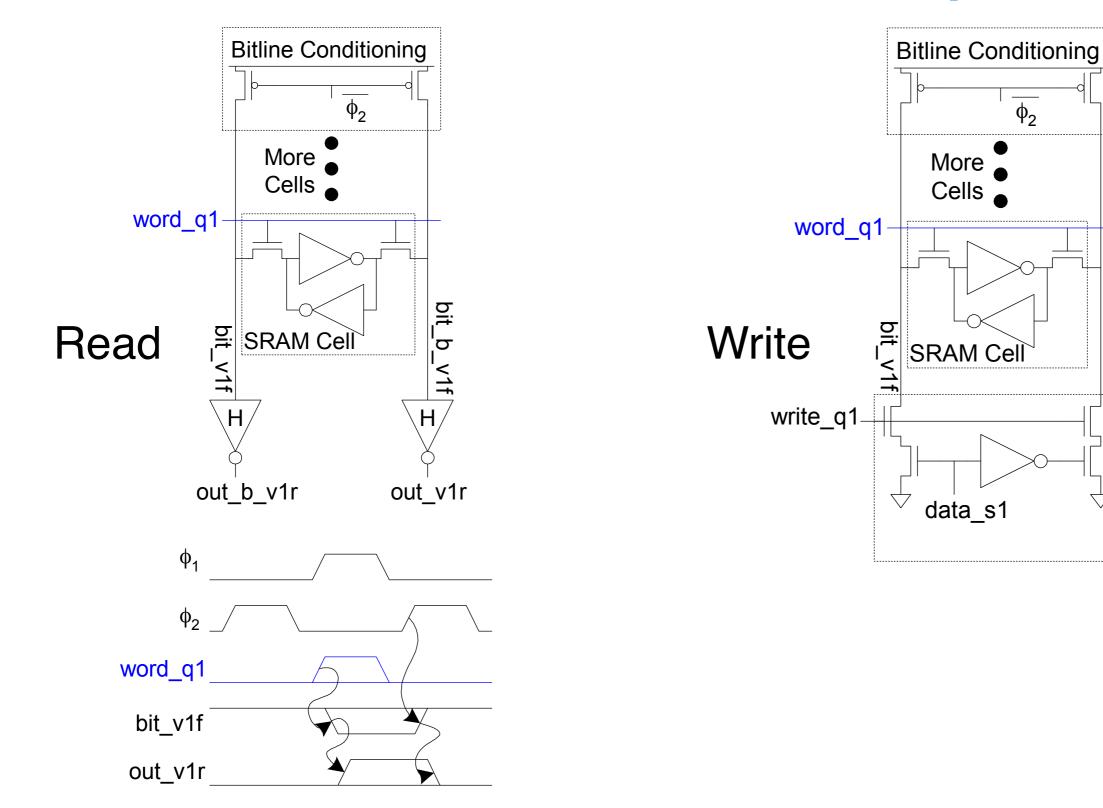


*Twisted Bitlines

- Sense amplifiers also amplify noise
 - Coupling noise is severe in modern processes
 - Try to couple equally onto bit and bit_b
 - Done by *twisting* bitlines



*SRAM Column Example



L09. Memory-2

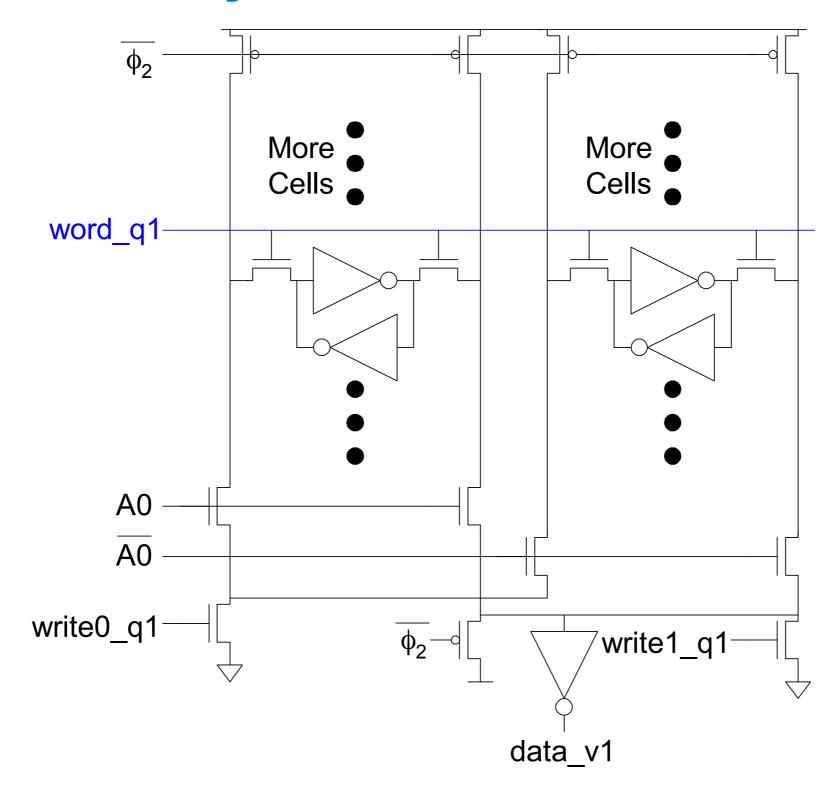
bit_b_v1f

*Column Multiplexing

• Recall that array may be folded for good aspect ratio

- Ex: 2 kword x 16 folded into 256 rows x 128 columns
 - Must select 16 output bits from the 128 columns
 - Requires 16 8:1 column multiplexers

*Ex: 2-way Muxed SRAM

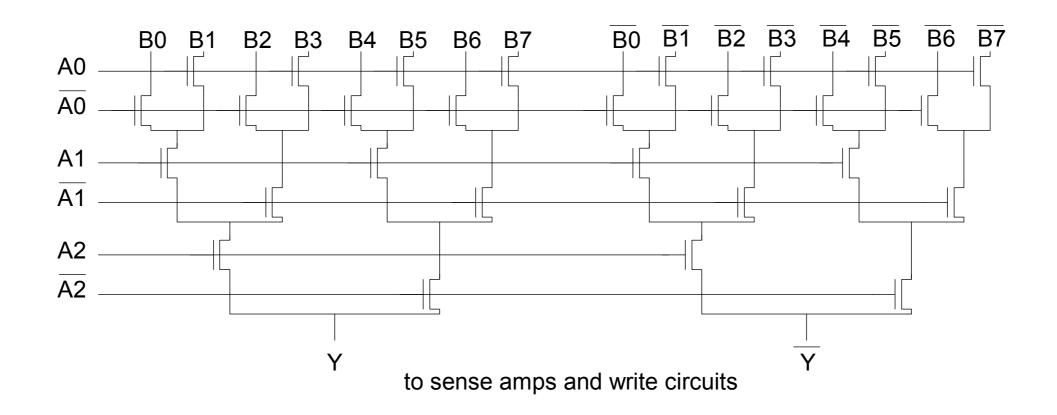


CENG4480

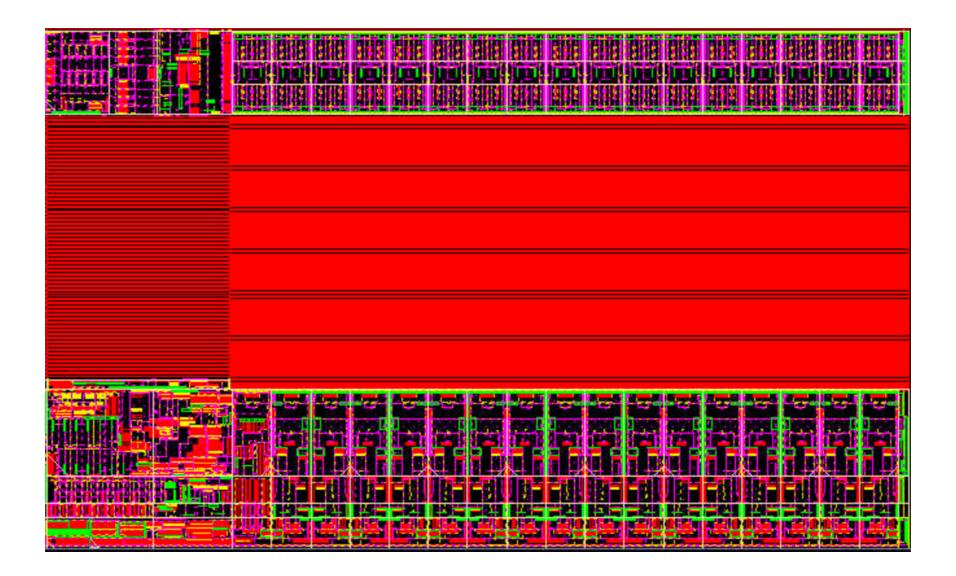
L09. Memory-2

*Tree Decoder Mux

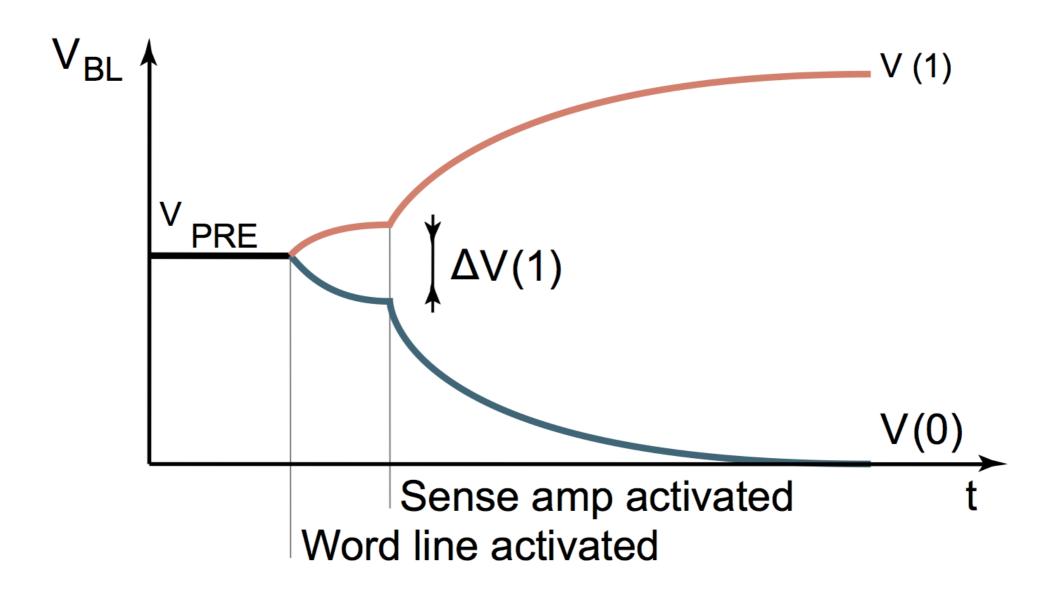
- Column mux can use pass transistors
 - Use nMOS only, precharge outputs
- One design is to use k series transistors for 2^k:1 mux
 - No external decoder logic needed



*SRAM from ARM



*Sense Amp Operation for 1T DRAM



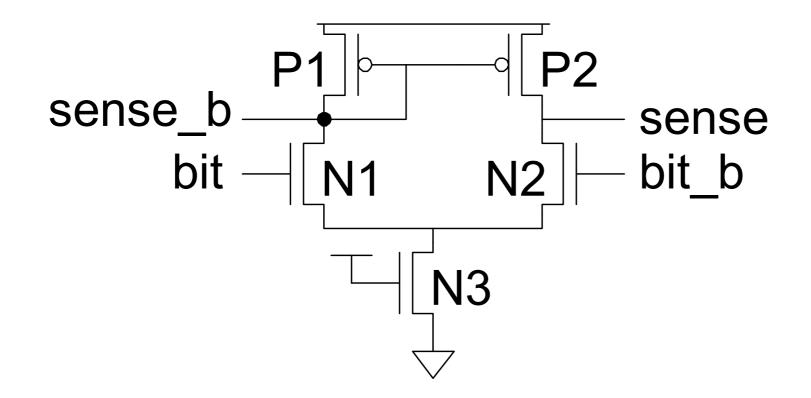
- 1T DRAM read is destructive
- Read and refresh for 1T DRAM

*Sense Amplifiers (DRAM)

- Bitlines have many cells attached
 - Ex: 32-kbit SRAM has 256 rows x 128 cols
 - 256 cells on each bitline
- $t_{pd} \propto$ (C/I) ΔV
 - Even with shared diffusion contacts, 64C of diffusion capacitance (big C)
 - Discharged slowly through small transistors (small I)
- Sense amplifiers are triggered on small voltage swing (reduce ΔV)

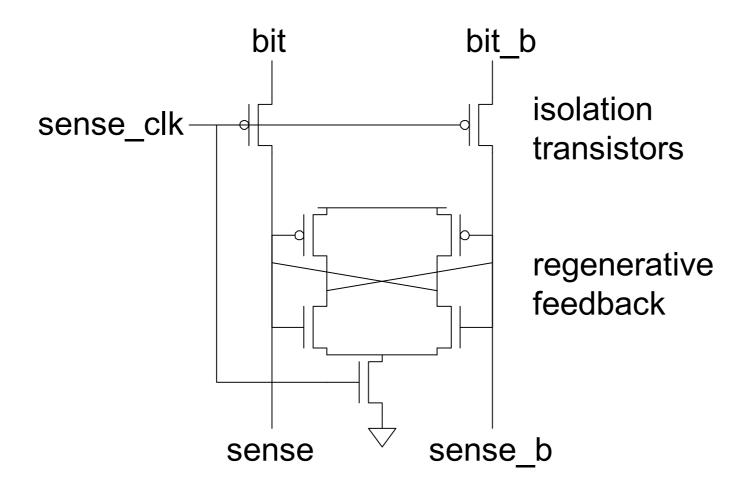
*Differential Pair Amp

- Differential pair requires no clock
- But always dissipates static power



*Clocked Sense Amp

- Clocked sense amp saves power
- Requires sense_clk after enough bitline swing
- Isolation transistors cut off large bitline capacitance



Thank You :-)



